is filled with a conductor to connect the wiring line in the first inner layer 12a to a wiring line in a layer provided on the other side of the core substrate 20, although the other side of the core substrate 20 is not shown in the drawing for simplification. The wiring line in the outermost layer 12, as formed, is exposed on the surface of the outermost built-up layer (insulation layer) 22b, and is subsequently covered with a solder resist layer 16 (which also covers the exposed surface of the outermost insulation layer 22b) so as to expose a connecting terminal 10, which represents an end portion of the wiring line, as seen in Fig. 13. Terminal 10 is then coated with solder 14. The connecting terminal 10 has a thickness of the order of 20 micrometers. The solder resist layer 16 has a thickness of the order of 40 micrometers, at the region covering the outermost insulation layer 12, and a thickness of the order of 20 micrometers at the region covering the wiring line layer 12.

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The connecting terminal 10 is formed in an elongated shape, as clearly seen in Fig. 20. The site of the terminal 10, to which an electrode terminal of a semiconductor device (not shown) is to be bonded, is at the end portion of the terminal 10 (i.e., on the line X-X' in the drawing). The reason why the connection terminal 10 is formed in an elongated shape is that variation in the amount of solder to be coated to the respective connecting terminals 10 must be restrained to reliably bond the electrode terminal of a semiconductor device to the connecting terminal 10 of the substrate.

The coating of the solder 14 to the surface of the connecting terminal 10 is carried out by a method in which a powder of solder is placed on the connecting terminal 10, and flux is then applied to the solder, after which the solder is coated to the terminal 10 by a reflow process. The method of coating solder to a connecting terminal using a powder of solder is